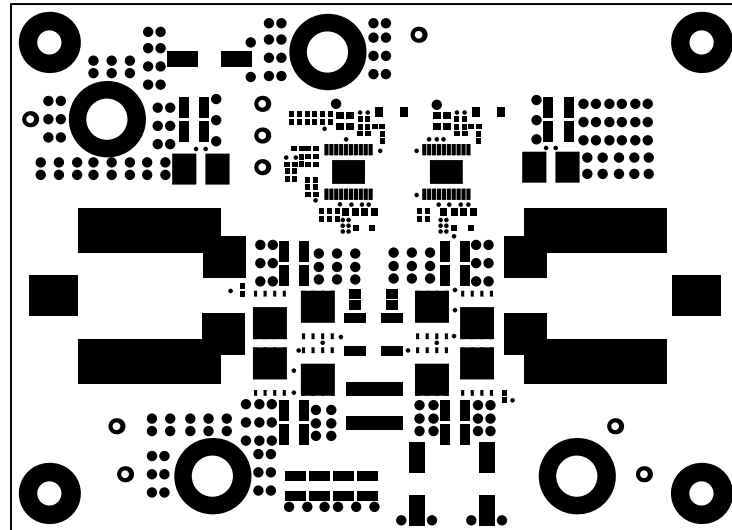
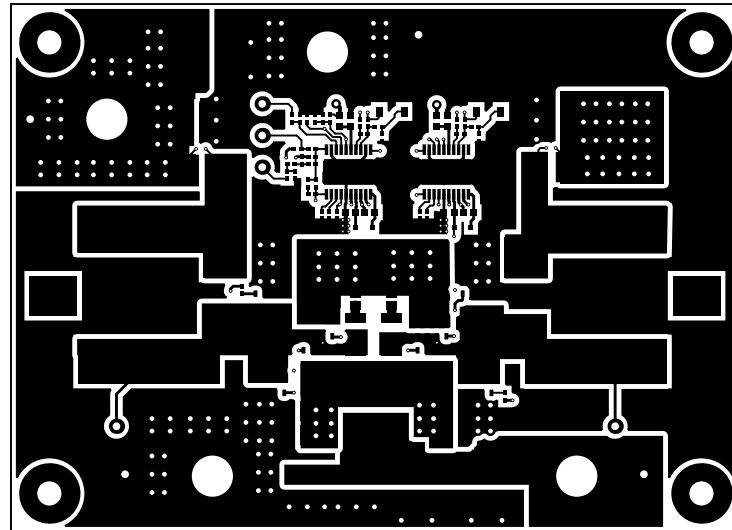


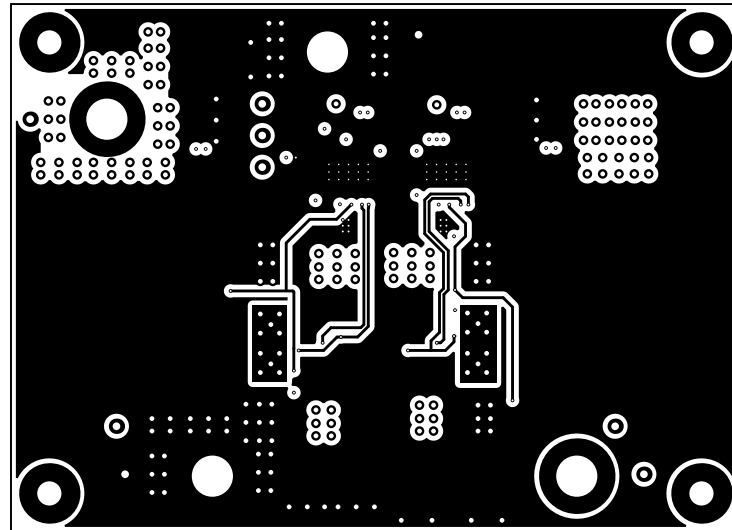
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01610		
PLOT NAME = Top Overlay	GENERATED : 12/14/2017 4:05:12 PM	TEXAS INSTRUMENTS	



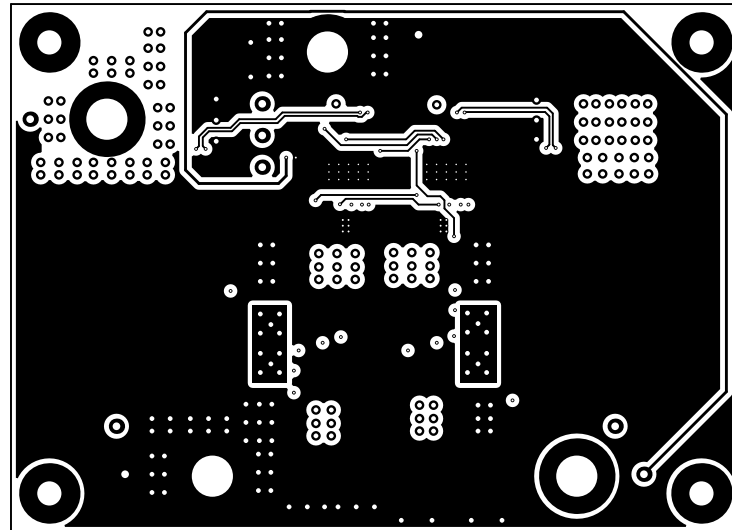
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01610		
PLOT NAME = Top Solder Mask	GENERATED : 12/14/2017 4:05:14 PM	TEXAS INSTRUMENTS	



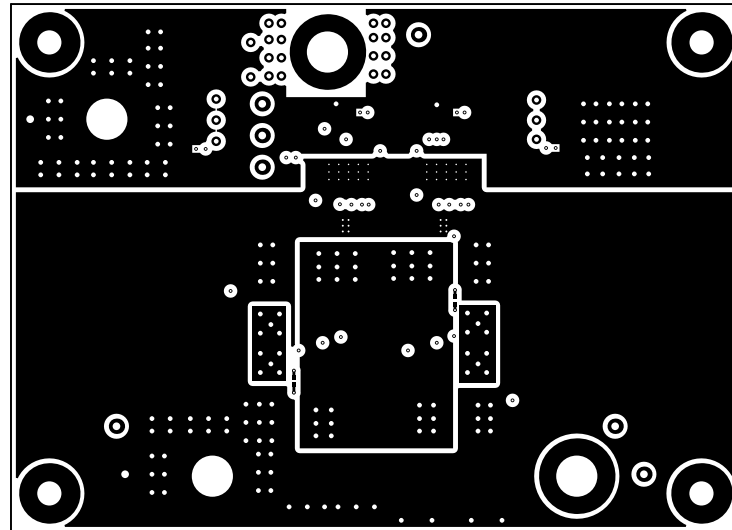
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01610		
PLOT NAME = Top Layer	GENERATED : 12/14/2017 4:05:16 PM	TEXAS INSTRUMENTS	



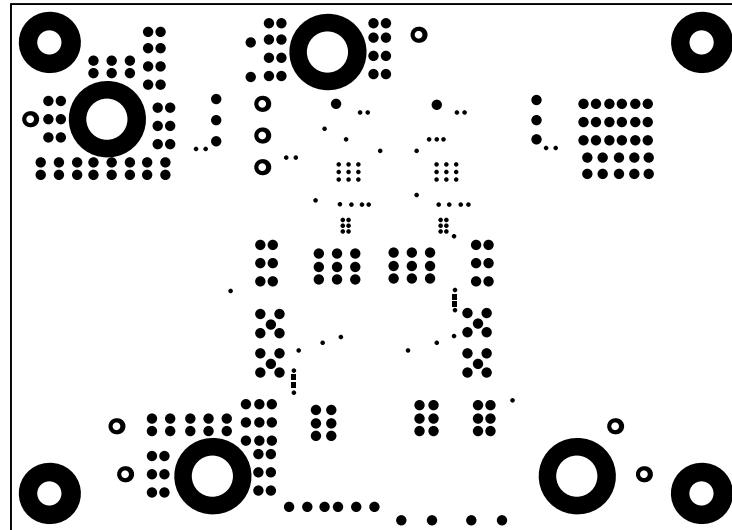
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01610		
PLOT NAME = Signal Layer 1	GENERATED : 12/14/2017 4:05:17 PM	TEXAS INSTRUMENTS	



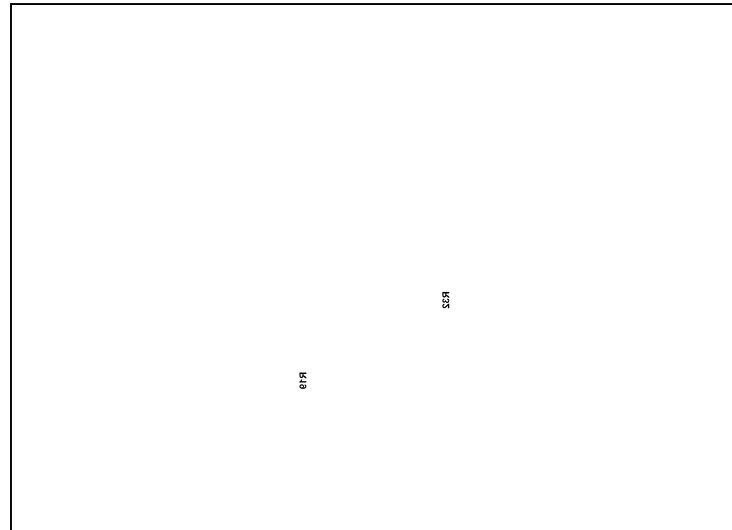
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01610		
PLOT NAME = Signal Layer 2	GENERATED : 12/14/2017 4:05:19 PM	TEXAS INSTRUMENTS	



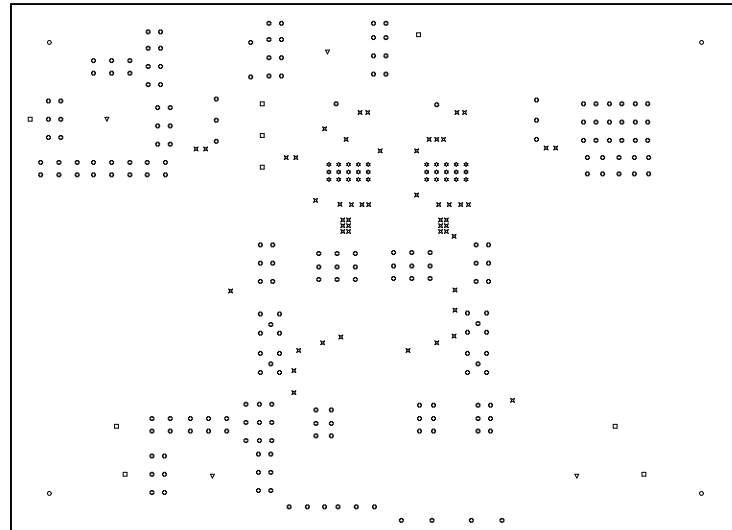
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01610		
PLOT NAME = Bottom Layer	GENERATED : 12/14/2017 4:05:20 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01610		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/14/2017 4:05:22 PM	TEXAS INSTRUMENTS	

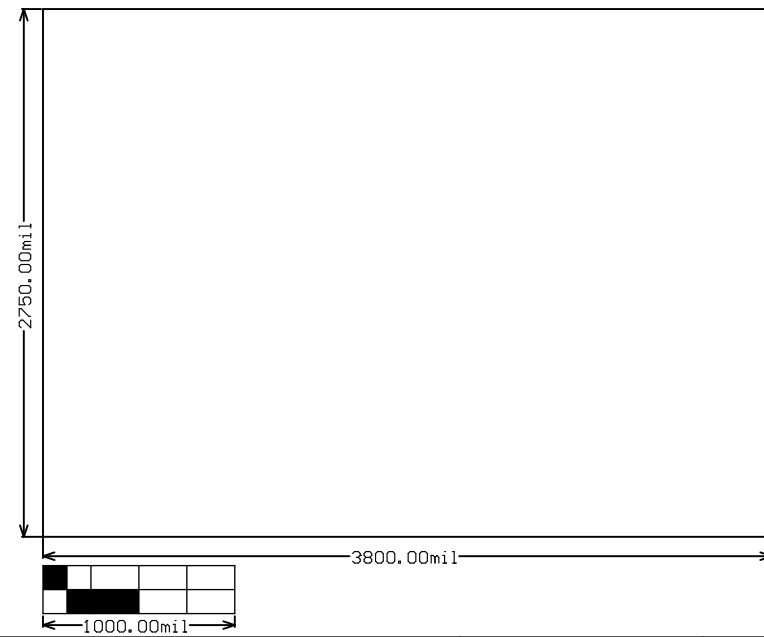


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01610		
PLOT NAME = Bottom Overlay	GENERATED : 12/14/2017 4:05:24 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	30	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	52	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	205	25.00mil (0.635mm)	PTH	Round	Top Layer - Bottom Layer	
□	9	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	214.57mil (5.450mm)	PTH	Round	Top Layer - Bottom Layer	
	304 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01610		
PLOT NAME = Drill Drawing	GENERATED : 12/14/2017 4:05:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01610	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01610		
PLOT NAME = Board Dimensions	GENERATED : 12/14/2017 4:05:31 PM	TEXAS INSTRUMENTS	

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